## **ISDCS 2023** The 6th International Symposium on Devices, Circuits and Systems (ISDCS) May 29-31, 2023, A Fully Virtual Conference



Organized by: Hiroshima University, Higashi-Hiroshima, Japan

(in collaboration with Indian Institute of Engineering Science and Technology, Shibpur, India)

# **Call for Papers**

### **A Fully Virtual Conference**



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### Approval in Process IEEE, Hiroshima Section

#### **Application/Inquiries**

HiSIM Research Center, Hiroshima University, Higashi-Hiroshima, Japan Email: contact-isdcs2023@ml.hiroshima-u.ac.jp International Symposium on Devices, Circuits and Systems (ISDCS) focuses on the recent innovations in Devices, Circuits, and Systems, highlighting the strong foundation in methodology and the integration of multidisciplinary approaches. Globally innovating scientists, researchers, and engineers, who change the ways in which devices and circuits are understood, optimized, and leveraged in a variety of systems and applications, are cordially invited to contribute their latest results.

### ISDCS Symposium (May 29 - 31, 2023)

**Scope:** Original contributions are solicited on topics covered under broad areas such as (but not limited to):

- Physics, Analysis, and Modeling of Devices for Different Applications
- Photonics and Optoelectronics of Advanced Materials
- Digital and Analog Circuits and Their System Applications
- Neural Networks & Neuromorphic Circuits and Systems
- Circuit Testing and Verifications
- IoT Circuits and Systems
- AI Circuits for Machine Learning Systems
- Beyond CMOS Circuits and Hybrid systems
- Intelligent Systems and Robotics
- Environment Electronics and Their Applications
- Visual Communications & Multimedia Signal Processing

The Program Committee invites original, unpublished, as well as review paper submissions on the above topics.

- Abstract submissions should be complete manuscripts, not exceeding one (1) page, but figures, tables, and bibliography can continue to the 2<sup>nd</sup> page.
- Camera-Ready version for accepted papers should be complete manuscripts, expected to be limited by four (4) pages (including figures, tables, and bibliography) in a standard IEEE two-column format.
- Author(s) must submit a final camera-ready version of these papers for inclusion in the proceedings.
- Accepted papers will be submitted for inclusion into IEEE Xplore.
- Each accepted contribution must have at least one full paid registration by the time the camera-ready paper is submitted for inclusion in the proceedings.
- > The committee reserves the right to remove from IEEE Xplore papers not presented at the symposium.

#### Abstract Submission link: <u>https://www.isdcs2023.hiroshima-u.ac.jp/</u>

#### Important Dates

Abstract Submission Deadline	:	April 6, 2023 (23:59 GMT)
Notification of Acceptance	:	April 29, 2023
Camera Ready Submission	:	May 22, 2023 (23:59 GMT)
Program Announcement	:	May 25, 2023